

Amendments to the Specification

Please replace the title with the following amended title:

TRANSFER MOLDING [APPARATUS AND] METHOD FOR MANUFACTURING
SEMICONDUCTOR DEVICES

**Please replace the CROSS REFERENCE TO RELATED APPLICATIONS
section on page 1, between the title and the heading "BACKGROUND OF THE
INVENTION" with the following section:**

CROSS REFERENCE TO RELATED APPLICATIONS

C This is a divisional application of application Serial No. 09/265,841, filed March
10, 1999, now U.S. Patent No. 6,267,577, which is hereby incorporated by reference in
its entirety for all purposes.
